

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1.(original): A solar cell module comprising a plurality of solar cell elements in a flat plate shape, and an inner lead for electrically connecting a bus bar electrode provided on a light receiving surface of one of the solar cell elements and a bus bar electrode provided on a non-light receiving surface of the other solar cell element adjacent thereto, wherein

the solar cell elements which are connected to each other by the inner lead are sealed into a filler, and

an edge along the longitudinal direction of the bus bar electrode and a portion from the edge to a predetermined distance inward therefrom are brought into direct contact with the filler.

2.(original): The solar cell module according to claim 1, wherein the bus bar electrode is joined to the inner lead with a solder at its center in the transverse direction.

3.(currently amended): The solar cell module according to claim 1 ~~or 2~~, wherein the width of the inner lead is smaller than the width of the bus bar electrode.

4. (currently amended): The solar cell module according to ~~any one of claims~~ claim 1 ~~to 3~~, wherein the solar cell element has a plurality of finger electrodes at least one ends of which are connected to the bus bar electrode formed on its light receiving surface and/or non-light receiving surface.

5.(original): The solar cell module according to claim 4, wherein the finger electrode is brought into direct contact with the filler over its whole length.

6.(original): The solar cell module according to claim 4, wherein the one end, connected to the bus bar electrode, of the finger electrode is coated with a coating member.

7.(original): The solar cell module according to claim 6, wherein the coating member in the finger electrode is a solder resist.

8. (currently amended): The solar cell module according to ~~any one of claims~~ claim 1 ~~to~~ 7, wherein a solder for joining the bus bar electrode and the inner lead contains Bi.

9. (currently amended): The solar cell module according to ~~any one of claims~~ claim 1 ~~to~~ 8, wherein a solder for joining the bus bar electrode and the inner lead contains Sn, and satisfies the following equation:

$$\Sigma(V_i W_i) < 2.8(\%)$$

(where i denotes the number of elements composing the solder,  $V_i$  denotes the contraction coefficient (%) at the time of solidification of each of the elements composing the solder,  $W_i$  denotes the percentage by weight of each of the elements composing the solder (the whole is taken as 1), and the sum  $\Sigma$  takes 1 to i)

10.(original): A solar cell module comprising a plurality of solar cell elements in a flat plate shape, and an inner lead for electrically connecting a bus bar electrode provided on a light receiving surface of one of the solar cell elements and a bus bar electrode provided on a non-light receiving surface of the other solar cell element adjacent thereto, wherein

the solar cell elements which are connected to each other by the inner lead are sealed into a filler,

an edge along the longitudinal direction of the bus bar electrode and a portion from the edge to a predetermined distance inward therefrom are coated with a coating member, and

the coating member is brought into direct contact with the filler.

11.(original): The solar cell module according to claim 10, wherein the coating member in the bus bar electrode is a solder resist.

12. (currently amended): The solar cell module according to claim 10 ~~or 11~~, wherein the bus bar electrode is joined to the inner lead with a solder at its center in the transverse direction.

13. (currently amended): The solar cell module according to ~~any one of claims claim 10 to 12~~, wherein the solar cell element has a plurality of finger electrodes at least one ends of which are connected to the bus bar electrode formed on its light receiving surface and/or non-light receiving surface.

14.(original): The solar cell module according to claim 13, wherein the one end, connected to the bus bar electrode, of the finger electrode is coated with the coating member.

15.(original): The solar cell module according to claim 14, wherein the coating member in the finger electrode also serves as a coating member in the bus bar electrode.

16. (currently amended): The solar cell module according to claim 14 ~~or 15~~, wherein the coating member in the finger electrode is a solder resist.

17. (currently amended): The solar cell module according to ~~any one of claims~~ claim 10 ~~to 16~~, wherein a solder for joining the bus bar electrode and the inner lead contains Bi.

18. (currently amended): The solar cell module according to ~~any one of claims~~ claim 10 ~~to 17~~, wherein a solder for joining the bus bar electrode and the inner lead contains Sn, and satisfies the following equation:.

$$\Sigma(V_i W_i) < 2.8(\%)$$

(where i denotes the number of elements composing the solder,  $V_i$  denotes the contraction coefficient (%) at the time of solidification of each of the elements composing the solder,  $W_i$  denotes the percentage by weight of each of the elements composing the solder (the whole is taken as 1), and the sum  $\Sigma$  takes 1 to i)

19.(original): A solar cell module comprising a plurality of solar cell elements in a flat plate shape, and an inner lead for electrically connecting a bus bar electrode provided on a light receiving surface of one of the solar cell elements and a bus bar electrode provided on a non-light receiving surface of the other solar cell element adjacent thereto, wherein

the inner lead and the bus bar electrode are electrically connected to each other with a solder, and

the solder contains Sn, and satisfies the following equation:

$$\Sigma(V_i W_i) < 2.8(\%)$$

(where i denotes the number of elements composing the solder,  $V_i$  denotes the contraction coefficient (%) at the time of solidification of each of the elements composing the solder,  $W_i$  denotes the percentage by weight of each of the elements composing the solder (the whole is taken as 1), and the sum  $\Sigma$  takes 1 to i)

20.(original): The solder cell module according to claim 19, wherein the solder contains Bi.

21.(original): The solder cell module according to claim 20, wherein the solder contains 3 to 85 % by weight of Bi.

22. (currently amended): The solar cell module according to ~~any one of claims~~ claim 19 ~~to 21~~, wherein the bus bar electrode is mainly composed of Ag, and the solder contains 0.5 to 6.5 % by weight of Ag.

23.(original): A solar cell module comprising:  
a plurality of solar cell elements in a flat plate shape;  
an inner lead for electrically connecting a bus bar electrode provided on a light receiving surface of one of the solar cell elements and a bus bar electrode provided on a non-light receiving surface of the other solar cell element adjacent thereto;  
an outer lead connected to ends of the plurality of solar cell elements which are connected to one another by the inner lead; and  
a coupling wiring for connecting the outer leads,  
the outer lead and the coupling wiring being electrically connected to each other with a solder mainly composed of tin, silver, and copper, and  
the bus bar electrode and the inner lead being electrically connected to each other with a solder mainly composed of tin, bismuth, and silver.

24.(original): The solar cell module according to claim 23, wherein the bus bar electrode and the outer lead are electrically connected to each other with a solder mainly composed of tin, bismuth, and silver.

25. (currently amended): The solar cell module according to claim 23 ~~or 24~~, wherein the composition of the solder mainly composed of tin, silver, and copper is 1.0 to 5.0 % by weight of silver, 0.4 to 7.0 % by weight of copper, and the remaining percent by weight of tin.

26. (currently amended): The solar cell module according to ~~any one of claims~~ claim 23 ~~to 25~~, wherein the composition of the solder mainly composed of tin, bismuth, and silver is 20 to 60 % by weight of bismuth, 0.5 to 5 % by weight of silver, and the remaining percent by weight of tin.